OKI Semiconductor ML7020

1200 bps MODEM for Remote Control Systems

GENERAL DESCRIPTION

The ML7020 is a 1200 bps modem LSI developed for remote control systems. The functions incorporated are those of a 1200 bps FSK modem conforming to ITU-T Recommendations V.23, DTMF signal generation and detection, call progress tone (CPT) generation and detection. Each functional block can be controlled via a 4-bit processor interface.

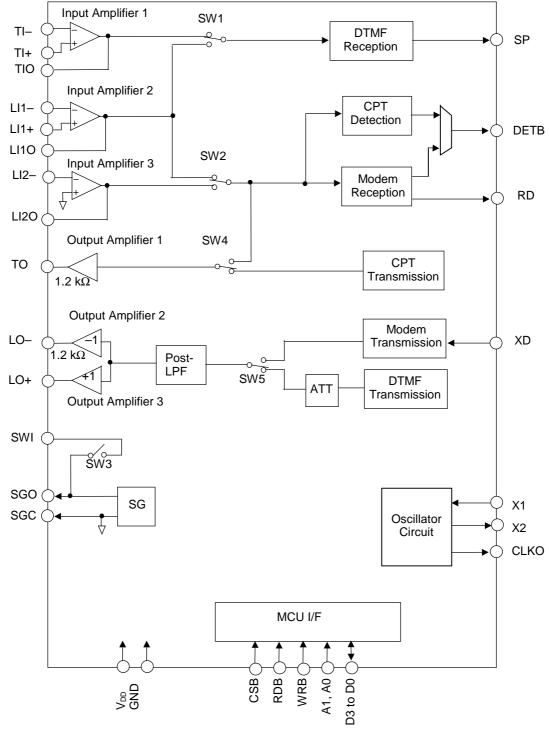
FEATURES

- Single 5 V power supply operation (V_{DD} : 4.5 to 5.5 V)
- Low power consumption: During operation: 5 mA typ.

During the power down mode: 7 µA typ.

- Built-in 1200 bps modem conforming to ITU-T V.23 recommendations
- Built-in DTMF signal generator with a switchable 6-dB attenuator
- Built-in DTMF detector (the input can be selected from either the line or the terminal)
- Built-in call progress tone generator. The output frequency can be selected from 400 Hz and 800 Hz.
- Built-in call progress tone detector
- Three analog input systems (switchable)
- Analog output for the line is of the differential type and can drive a 600 Ω line transformer.
- \bullet Analog output for the terminal is of the single-ended type and can drive a 1.2 k Ω load.
- \bullet Built-in switch for selecting the 600 Ω termination
- 4-Bit processor interface
- Built-in oscillator circuit for a 3.579545 MHz crystal
- Package: 32-Pin plastic SSOP (SSOP32-P-430-1.00-K) (Product name: ML7020MB)

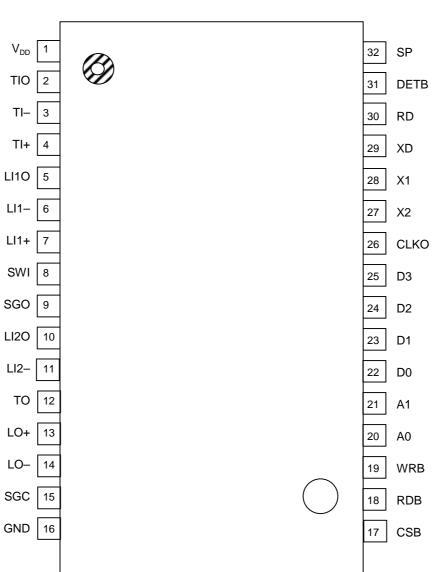
BLOCK DIAGRAM



* CPT: Call progress tone

* The state shown of each switch is that when the register is set to "0".

PIN CONFIGURATION (TOP VIEW)



32-Pin plastic SSOP

PIN DESCRIPTIONS

Pin No.	Symbol	I/O	Description
1	V _{DD}		Power supply pin. Connect a +5 V power supply to this pin.
2	TIO	0	The output pin of the input amplifier 1. See Figure 1. For the sake of noise reduction, connect a capacitor between this pin and $TI-$ (3) so as to attenuate high frequency components above 10 kHz.
3	TI–	I	The inverting input pin for the input amplifier 1. When the input amplifier 1 is not used, connect pin TIO (2) to pin TI– (3), and connect pin TI+ (4) to pin SGO.
4	TI+	I	The non-inverting input pin for the input amplifier 1.
5	LI1O	0	The output pin for the input amplifier 2. See Figure 1. For the sake of noise reduction, connect a capacitor between this pin and $LI1-$ (6) so as to attenuate high frequency components above 10 kHz.
6	LI1-	I	The inverting input pin for the input amplifier 2. When the input amplifier 2 is not used, connect pin LI1O (5) and LI1– (6), and connect pin LI+ (7) to pin SGO.
7	LI1+	I	The non-inverting input pin for the input amplifier 2.
8	SWI	I	The input pin for SW3. This pin is connected internally to SGO (9) when SW3 is to be made ON.
9	SGO	0	The signal ground output pin for external circuits. A voltage of about $V_{\mbox{\tiny DD}}/2$ is output from this pin.
10	LI2O	ο	The output pin for the input amplifier 3. See Figure 1. For the sake of noise reduction, connect a capacitor between this pin and LI2– (10) so as to attenuate high frequency components above 10 kHz.
11	LI2–	I	The inverting input pin for the input amplifier 3. When the input amplifier 3 is not used, connect pin LI2O (10) and LI2– (11).
12	то	0	The output pin of the output amplifier 1. Can drive a load of 1.2 k Ω or more.
13	LO+	0	The non-inverting output pin for the output amplifier 2. See Figure 2 for details of connecting a peripheral circuit.
14	LO-	0	The inverting output pin of the output amplifier 2. See Figure 2 for details of connecting a peripheral circuit.
15	SGC	ο	The signal ground output pin for internal circuits. A voltage of about $V_{DD}/2$ is output from this pin. Connect a 1 μ F capacitor between SGC (15) and GND (16).
16	GND		The ground pin for the LSI. Connect a 0 V input to this pin.
17	CSB	I	The chip select pin for the processor interface. Reading and writing are possible when this input is "0". Reading and writing are disabled when this input is "1".
18	RDB	I	The read control pin for the processor interface. Data can be read from the LSI when this pin is "0".
19	WRB	I	The write control pin for the processor interface. Data is written into this LSI at the rising edge of the WR signal.
20	A0	1	The address input pin A0 for the processor interface.

Pin No.	Symbol	I/O	Description
21	A1	I	The address input pin A1 for the processor interface.
22	D0	10	The data input/output pin D0 for the processor interface.
23	D1	ю	The data input/output pin D1 for the processor interface.
24	D2	ю	The data input/output pin D2 for the processor interface.
25	D3	10	The data input/output pin D3 for the processor interface.
26	CLKOUT	0	The 3.579545 MHz oscillator circuit output pin.
27	X2	0	The pins for connecting a 3.579545 MHz crystal. The capacitors and the
28	X1	I	feedback resistor are internally connected to these pins. When inputting an external clock, connect the input to the X1 pin via a 1000 pF capacitor and leave the pin X2 open.
29	XD	I	The modem transmit data input pin. The "1" level corresponds to the mark data and the "0" level corresponds to the space data.
30	RD	0	The modem receive data output pin. The mark and space data are the same as for XD. A mark is output when no carrier is detected.
31	DETB	0	The pin for outputting the carrier detect signal of the modem or the call progress tone detector output. The detection result corresponding to the respective operating mode is output from this pin. A "0" indicates detection and a "1" indicates non-detection.
32	SP	ο	The DTMF reception detection output pin. A "0" indicates detection and a "1" indicates non-detection.



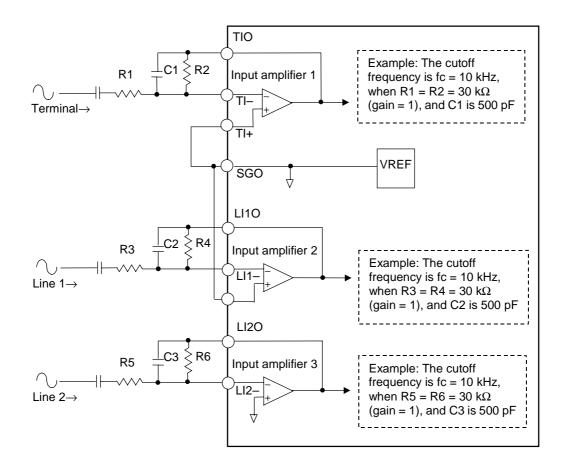


Figure 1 Input amplifier 1 to 3 interface

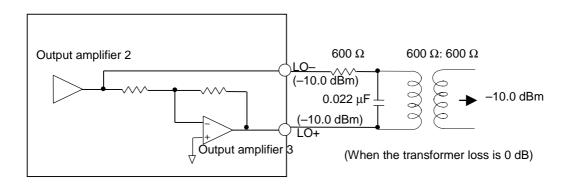


Figure 2 Output amplifier 2, 3 interface example

–0.3 to V_{DD} + 0.3

–0.3 to $V_{\rm DD}$ + 0.3

-55 to +150

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V

V

°C

dissipation

Analog input voltage

Digital input voltage

Storage temperature range

Symbol Condition Rating Unit Parameter ٧ Power supply voltage V_{DD} — -0.3 to +7.0 Permissible power P_D to 130 mW Shorted to V_{DD} or ground. Output short circuit current to 60 I_{SHT} mΑ

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ABSOLUTE MAXIMUM RATINGS

RECOMMENDED OPERATING CONDITIONS

 V_{AIN}

 V_{DIN}

 $\mathsf{T}_{\mathsf{stg}}$

				$(V_{DD} = 4.5)$	to 5.5 V, T	a = –40 t	o +85°C)
Parameter		Symbol	Condition	Min.	Тур.	Max.	Unit
Power	supply voltage	V _{DD}	—	4.5	5.0	5.5	V
Operat	ing temperature range	Та	_	-40	_	+85	°C
High le	evel input voltage	V _{IH}	Digital input pins	$0.8 \times V_{DD}$	_	V_{DD}	V
Low lev	vel input voltage	V _{IL}	Digital input pins	0	_	$0.2 \times V_{DD}$	V
Digital	input rise time	t _{ir}	Digital input pins	_	_	50	ns
Digital	input fall time	t _{if}	Digital input pins	_	—	50	ns
Digital	Digital output load		Digital output pins	_	—	100	рF
Bypass	Bypass capacitor for SGC		Between SGC and GND	1	—		μF
Bypass	s capacitor for V_{DD}	C _{VG}	Between V_{DD} and ground	10	—		μF
	Oscillating frequency	_	_		3.579545		MHz
	Frequency deviation	_	25 ±5°C	-100	—	+100	ppm
Crystal	Temperature characteristics	_	In the temperature range –40 to +85°C	-50	—	+50	ppm
C Z	Equivalent series resistor	_	_	_	_	90	Ω
	Production load capacitance	_	—	_	16	_	pF
	Input clock frequency deviation		Values when an X1 external clock		_	+0.1	%
Input c	lock duty ratio	DUTY	is input	40	_	60	%

ELECTRICAL CHARACTERISTICS

DC Characteristics

			$(V_{DD} = 4.5)$	5 to 5.5 V,	Ta = -40 t	o +85°C)
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Power supply current	I _{DD1}	During operation (modem transmission/reception mode)*1	0	5.0	10.0	mA
	I _{DD2}	During operation (tone 1 mode)*1	0	5.0	10.0	mA
	I _{DD3}	During operation (tone 2, tone 3 modes)*1	0	6.0	11.0	mA
	I _{DD4}	During power down	0	7.0	100	μA
Input leak current	I _{IH}	$V_{I} = V_{DD}$	—	—	2.0	μA
	I _{IL}	$V_i = 0 V$	—	—	0.5	μA
High level output voltage	V _{OH}	I _{OH} = -100 μA	V _{DD} -0.1	_	V_{DD}	V
Low level output voltage	V _{OL}	$I_{OL} = 100 \ \mu A$	0	0.05	0.1	V
Input capacitance	C _{IN}			5		pF

*1: See Table 3 for details of the modes.

Analog Interface

				$(V_{DD} = 4.5)$	o to 5.5 V,	Ia = -40 t	o +85°C)
Parameter	Symbol	Condit	Min.	Тур.	Max.	Unit	
Input resistance	R _{IN}	TI–, TI+, LI1–,	TI–, TI+, LI1–, LI1+, LI2–				MΩ
	R _{L1}	TIO, LI1O	, LI2O	20		_	kΩ
Output load resistance	R_{L2}	TO (Output amplitud	le 1 Vpp or less)	1.2		_	kΩ
	R _{L3}	LO–, LO+ (differe	ential outputs)	1.2	_	_	kΩ
Output load capacitance	CL	Analog ot	Analog outputs			100	pF
Output impodonce	R _{ox1}	TIO, LI1O, LI2O, TO			10		Ω
Output impedance	R _{ox2}	LO–, LO+, SGO		_	10	_	Ω
	V ₀₁	TIO, LI1O, LI2O, TO, LO–, LO+, SGC		_	$V_{DD}/2$	_	V
Output DC voltage	V _{O2}	SGO		V _{DD} /2 -0.1	V _{DD} /2	V _{DD} /2 +0.1	V
Out of band on minut	V _{S1}		4 to 8 kHz		-60	-20	dBm
Out-of-band spurious response	V _{S2}	LO–, LO+	8 to 12 kHz	_	-80	-40	dBm
	V _{S3}	(Differential outputs)	12 kHz to (4 kHz each)	_	-80	-60	dBm
SW3 impedance	R_{SW3}	SW3	3	_	15	30	Ω
Output current	I _{sgo}	SGO pin (includi	ng via SW3)	-0.6		0.6	mA

 $(V_{DD} = 4.5 \text{ to } 5.5 \text{ V}. \text{ Ta} = -40 \text{ to } +85^{\circ}\text{C})$

AC Characteristics (DTMF Section)

			$(V_{DD} = 4)$.5 to 5.5	5 V, Ta =	–40 to	+85°C)
Parameter	Symbol	Condition			Тур.	Max.	Unit
Transmit level	V _{dttl}	LO–, LO+_Differential *1	Lower group tone	-7.0	-4.5	-3.0	dBm
	V _{dtth}		tone		-2.5	-1.0	dBm
Transmit signal level relative value	V_{DTDF}	(Higher group tone) – (lov	ver group tone)	1	2	3	dB
Transmit signal frequency deviation	f _{DDT}	Relative to the nomina	I frequency	-1.5	—	+1.5	%
Transmit signal distortion rate	THD _{DT}	(Harmonic waves) – (fund	lamental wave)	—	—	-23	dB
DTMF detection level	V_{DETDT}	For one freque	ency	-42	—	-6	dBm
DTMF non-detection level	V _{REJDT}	For one freque	ency		—	-60	dBm
Detection frequency band	f _{DETDT}	Relative to the nomina	l frequency		_	±1.5	%
Non-detection frequency band	f _{REJDT}	Relative to the nomina	I frequency	±3.8		_	%
Level difference between two received frequencies	V _{TWIST}	(Higher group tone) – (lov	ver group tone)	-6	_	+6	dB
Permissible received noise level	L _{OSSR6}	(Noise level) – (tone level) 0.3 to 3.4 kHz			-12	_	dB
Received dial tone elimination ratio	V_{REJCP}	380 to 420 H	łz	37	53	_	dB
Signal repetition period	t _c			120	_	_	ms
Input signal persistence	t _s		Detection	49			ms
duration	t _i	During the tone 1, tone 2,	Non-detection	_	_	24	ms
Signal quiet duration	t _p	and loop back modes.		30	_	—	ms
Instantaneous break	t _{ba}	See Figure 3 and Table 3	SP = 0		_	0.4	ms
protection period	t _{bb}	for details.	SP = 1	_	_	10	ms
Detection delay time	t _a			24	41	49	ms
Detection hold time	t _d			24	28	35	ms
SP delay time	t _{sp}			0.2	0.6	1.0	ms
Signal repetition period	t _c	During the tone 3 mode.		60	—	—	ms
Input signal persistence	t _s	See Figure 3 and Table 3	Detection	35	_	—	ms
duration	t	for details.	Non-detection	—	—	10	ms
Signal quiet duration	t _p			21			ms
Instantaneous break	t _{ba}		SP = 0		—	0.4	ms
protection period	t _{bb}		SP = 1		—	3.0	ms
Detection delay time	t _q			12	26	37	ms
Detection hold time	t _d			15	20	27	ms
SP delay time	t _{sp}			0.2	0.6	1.0	ms
ATT attenuation	V _{ATT}	Relative to the ATT = "	0" reference	-7.5	-6	-4.5	dB

 $(V_{DD} = 4.5 \text{ to } 5.5 \text{ V}, \text{ Ta} = -40 \text{ to } +85^{\circ}\text{C})$

Note: 0 dBm = 0.775 Vrms

*1: The value will be 6 dB smaller for pin LO+ or pin LO– alone.

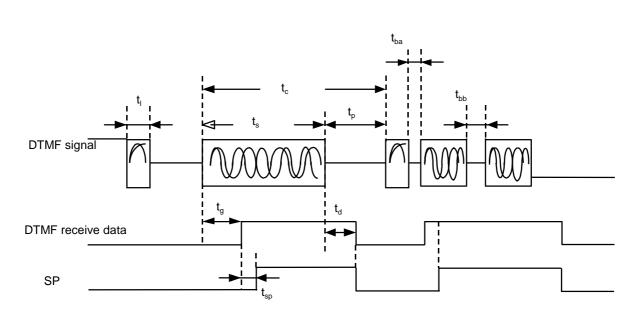


Figure 3 DTMF reception timing

- t_s: Input signal persistence duration (detection) Normal reception is made when the input signal persistence duration is equal to t_s or more.
- t_I: Input signal persistence duration (non-detection) The input signal is ignored when the input signal persistence duration is less than t_I, and the SP and DTMF receive data are not output.
- t_p: Signal quiet duration

The DTMF receive data and SP are reset if the input continues to be in the no-signal condition for a duration equal to t_p or longer.

Also, even if the receive data changes during DTMF signal reception, SP continues to be "1" and the DTMF receive data may remain in the initial value and may not change, if the signal quiet duration is less than t_p (including when it changes without any instantaneous break).

- t_{ba}: Instantaneous break protection period 1
 This is applicable to the period after the input signal has arrived and until the timing when SP becomes "1".

 In other words, SP and DTMF receive data are output normally even if a no-signal condition of a duration less than t_{ba} occurs.
- t_{bb} : Instantaneous break protection period 2 This is applicable when SP is "1" (during output of the receive data). In other words, SP and the DTMF receive data are not reset even if a no-signal condition of a duration less than t_{bb} occurs during signal reception.
- t_c : For ensuring normal reception, make sure that the signal repetition period is equal to t_c or more.
- t_g: Detection delay time

The DTMF receive data is output with a delay of t_g relative to the appearance of the input signal.

t_d: Detection hold time

The output of SP or the DTMF receive data is stopped with a delay of t_d after the termination of the input signal.

t_{sp}: SP delay time

SP is output after a delay of t_{sp} relative to the output of the DTMF receive data. Therefore, latch the DTMF receive data when the rising edge of SP is detected.

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AC Characteristics (Modem Section)

ne characteristics (into			(V _D	_D = 4.5 to	5.5 V, T	a = -40 t	o +85°C)
Parameter	Symbol	Condition	Condition				Unit
Modem transmit level	V _{AOM}	LO–, LO+ Differ	ential	-6.0	-4.0	-2.0	dBm
Transmit signal level relative value	$V_{\rm DM}$	(Mark signal) – (spa	ce signal)	-1.5	0	+1.5	dB
Transmit carrier	f _M		XD = 1	1292	1300	1308	Hz
frequency	f _s		XD = 0	2092	2100	2108	Hz
Receive signal level	V _{AI}	Level of LI1O and	d LI2O	-51	—	-6	dBm
	V _{ON}	Level of LI1O and LI2O	$OFF\toON$	—	-44.5	-42	dBm
Carrier detection level	V _{OFF}	1700 Hz	$ON\toOFF$	-51	-46.5	—	dBm
Carrier detection hysteresis	V _{HYS}	Ι			2	_	dB
Carrier detection delay time	t _{CDD}	OFF ightarrow -30~d	Bm	5	10	15	ms
Carrier detection hold time	t _{CDH}	-30 dBm \rightarrow C	23	28	34	ms	
Demodulation bias distortion	D _{BS}	1200 bps, 1:1 pa	attern	-10	_	+10	%

Note: RD is fixed at "1" when the carrier detector is OFF.

AC Characteristics (CLKO)

		(V _D	_D = 4.5 to	5.5 V, T	a = -40 te	o +85°C)
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Output emplitude	V _{COH}		$0.9 \times V_{DD}$		V_{DD}	V
Output amplitude	V _{COL}	CL = 100 pF	0	_	$0.1 \times V_{DD}$	V

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				$(V_{DD} =$	4.5 to 5.5	V, Ta = −40) to +85°C)
Parameter	Symbol	C	Condition	Min.	Тур.	Max.	Unit
Transmit level	V _{CPT}		Pin TO	-21.5	-20.0	-18.5	dBm
Tropomit froquency	£		During 400 Hz output	380	400	420	Hz
Transmit frequency	f _{CPT}	Pin TO	During 800 Hz output	780	800	820	Hz
Distortion rate	THD _{CPT}		Pin TO	_	_	-23	dB
Detection level	V_{DETCP}	400 Hz, leve	400 Hz, level of LI1O and LI2O		_	-6	dBm
Non-detection level	V _{REJCP}	400 Hz, leve	400 Hz, level of LI1O and LI2O		_	-60	dBm
Detection frequency	f _{DETCP}		—	360	_	440	Hz
Non-detection				510	_	_	Hz
frequency	f_{rejCP}		—	_	_	300	Hz
Detection	t _{DETCP}		Detection	30	_	_	ms
persistence period	t _{REJCP}	See Figure 4	. Non-detection		—	10	ms
Detection delay time	t _{DELCP}			10	17	30	ms
Detection hold time	t _{HOLCP}			10	17	30	ms

AC Characteristics (Call Progress Tone Section)

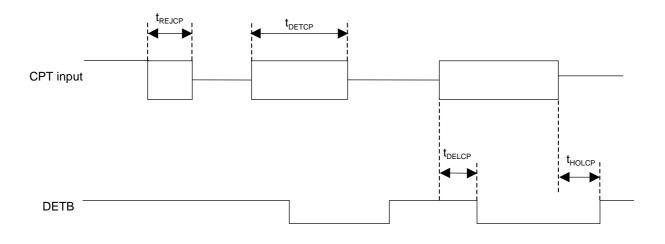


Figure 4 Call progress tone detection timing

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AC Characteristics (Processor Interface)

			$(V_{DD} = 4.5)$	to 5.5 V,	Ta = -40 t	o +85°C)
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Write signal period	Pw		2000	—	_	ns
Write signal width	T _w		100	—	_	ns
Read signal width	T _R		200	_	_	ns
Address data setup time	T _{AW1}		10	_	_	ns
	T _{AR1}		80	—	—	ns
Address data hold time	T _{AW2}	-	50	—	—	ns
	T _{AR2}		10		—	ns
Chip select setup time	T _{CW1}	See Figure 5.	10		—	ns
Chip select setup time	T _{CR1}		80	_	_	ns
Chin coloct hold time	T _{CW2}		50	—	_	ns
Chip select hold time	T _{CR2}		10	—	_	ns
Data setup time	T _{DW1}		110	_	_	ns
Data hold time	T _{DW2}		20	—	_	ns
Data output delay time	t _{pd1}		20	60	150	ns
Data output hold time	t _{pd2}		20	40	100	ns

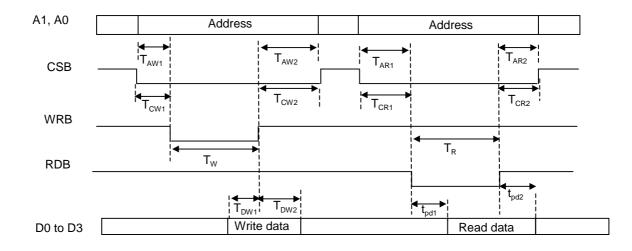


Figure 5 Processor interface timing

FUNCTIONAL DESCRIPTION

Description of Processor Interface

• List of Registers

Table 1	List of processor interface registers	
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A1	A0	R/W	D3	D2	D1	D0
0	0	W	PBG3	PBG2	PBG1	PBG0
0	1	R/W	SW1 CONT	MODE2	MODE1	MODE0
1	0	R/W	SW3 CONT	SW2 CONT	CPTG ON	CPT800
1	1	R/W	SW5 CONT	SW4 CONT	MOD-DT ON	ATT
0	0	R	PBR3	PBR2	PBR1	PBR0

* Data written into the registers other than the register [(A1, A0) = (0,0)] can be read out.

• PBG3 to 0/PBR3 to 0

The registers PBG3 to 0 are used for setting the DTMF transmit data.

The registers PBR3 to 0 are used for reading the DTMF receive data.

The output frequency does not change even if the code is changed during transmission.

Table 2 shows the data assignments.

D3	D2	D1	D0			Higher group	
PBG3/	PBG2/	PBG1/	PBG0/	CODE	Lower group frequency (Hz)	frequency (Hz)	
PBR3	PBR2	PBR1	PBR0				
0	0	0	1	1 697		1209	
0	0	1	0	2	697	1336	
0	0	1	1	3	697	1477	
0	1	0	0	4	770	1209	
0	1	0	1	5	770	1336	
0	1	1	0	6	770	1477	
0	1	1	1	7	852	1209	
1	0	0	0	8	852	1336	
1	0	0	1	9	852	1477	
1	0	1	0	0	941	1336	
1	0	1	1	*	941	1209	
1	1	0	0	#	941	1477	
1	1	0	1	А	697	1633	
1	1	1	0	В	770	1633	
1	1	1	1	С	852	1633	
0	0	0	0	D	941	1633	

Table 2 DTMF transmit/receive data assignments

^{*} Immediately after switching ON the power, use the LSI only after clearing the control registers using the power down mode.

• MODE2 to MODE0

These registers are used for setting the mode. The contents of setting are shown in Table 3.

				Operation of different blocks					
MODE2	MODE1	MODE0	Mode name	Modulator	Demodulator	DTMF	DTMF	CPT	CPT
				section	section	transmission	reception	transmission	reception
0	0	0	Modem transmission	0	-	-	-	0	-
0	0	1	Modem reception	Ι	0	-	Ι	0	_
0	1	0	Tone 1 (Note 1)	-	-	-	0	0	_
0	1	1	Tone 2 (Note 1)	_	_	0	0	0	0
1	0	0	Tone 3 (Note 1)	-	-	0	0	0	0
1	0	1	Loop back (Note 2)	0	О	0	0	_	_
1	1	0	Test			LSI interna	al test		
1	1	1	Power down (Note 3)	-	-	-	-	-	-

Table 3 List of mode settings

*[O]: Operating condition, [-]: Power down condition

Note 1: Tone 1, 2, 3 modes

The DTMF detection timing is different in the tone 1, 2, loop back modes from that in the tone 3 mode.

In the tone 3 mode, the DTMF detection goes into the high speed detection mode. In this mode, since the detector can make incorrect detection due to voice signals or noise, avoid using the tone 3 mode if there is any margin available in the timing.

Note 2: Loop back mode

The modem loop back mode is initiated when SW5CONT is High and MOD-DT_ON is High. (The data input in XD is output from RD via the internal circuits.)

The DTMF loop back mode is initiated when SW5CONT is Low and MOD-DT_ON is High. (The data set in PBG3 to PBG0 is latched at the rising edge of MOD-DT_ON, and is output at PBR3 to PBR0 via the internal circuits.)

Note 3: Power down mode

NOLE 5.	Fower down mode					
	The conditions when the LSI is put in the power down mode are listed below.					
	Each blocks:	Stop operating and the internal circuits are reset.				
	Analog output pins:	Go to the high-impedance state				
	DETB, RD, CLKO pins:	High level				
	SP, X2 pins:	Low level				
	Processor interface registers:	Low level (excepting SW1CONT, MODE2, 1, 0)				

• SW1CONT

This is the switch for selecting the DTMF reception input.

- 0: The input amplifier 1 is connected to the DTMF reception circuit.
- 1: The input amplifier 2 is connected to the DTMF reception circuit.
- SW2CONT
 - This is the switch for selecting the modem reception and CPT detection inputs.
 - 0: The input amplifier 2 is connected to the modem reception circuit and the CPT detection circuit.
 - 1: The input amplifier 3 is connected to the modem reception circuit and the CPT detection circuit.
- SW3CONT

This is the switch for external circuits, and can be used for connecting the termination, etc. 0: The switch goes into the OFF state.

1: The switch goes into the ON state. (The SWI pin and the SGO pin are connected together.)

• SW4CONT

This is the switch for selecting the signal (TO) of the output amplifier 1.

- 0: The CPT transmit output is connected to the output amplifier 1.
- 1: The output signal of SW2 is connected to the output amplifier 1.
- SW5CONT

This is the switch for selecting the signal (LO–, LO+) of the output amplifier 2.

- 0: The DTMF transmit output is connected to the output amplifier 2.
- 1: The modem transmit output is connected to the output amplifier 2.

Set this to "1" during the modem transmit mode and set this to "0" during the DTMF transmit mode.

• CPTG_ON

This register is used for the ON/OFF control of call progress tone transmission.

0: CPT transmission becomes OFF and the signal is not output.

1: CPT transmission becomes ON and the signal is output.

• CPT800

This selects the frequency of call progress tone transmission. 0: A 400 Hz signal is output. 1: An 800 Hz signal is output.

• MOD-DT_ON

This is used for the ON/OFF control of modem transmission or DTMF transmission.

The transmission function is made ON/OFF of the block corresponding to the selected mode.

0: Modem transmission or DTMF transmission become OFF and the signal is not output.

1: Modem transmission or DTMF transmission become ON and the signal is output.

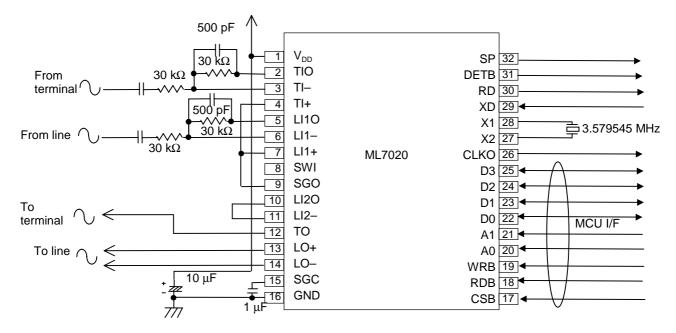
In the DTMF transmission mode or in the DTMF loop back mode, PBG3 to 0 are latched at the rising edge of MOD-DT_ON.

Set this to "0" during the modem reception mode and the tone 1 mode.

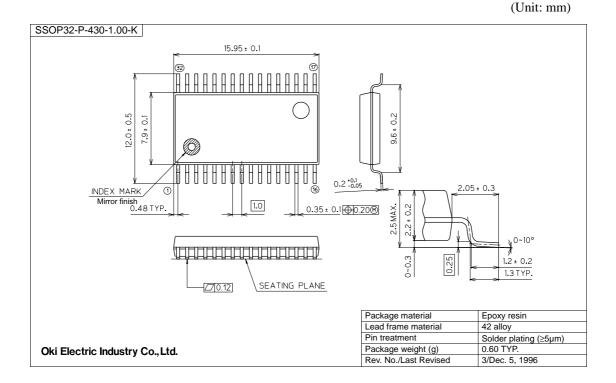
 \bullet ATT

This controls the attenuator of the DTMF transmission section. 0: No attenuator is inserted. The DTMF transmit signal is output as it is. 1: A -6 dB attenuator is inserted in the DTMF transmission section.

APPLICATION CIRCUIT EXAMPLE



PACKAGE DIMENSIONS



Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage.

Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

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- 2. The outline of action and examples for application circuits described herein have been chosen as an explanation for the standard action and performance of the product. When planning to use the product, please ensure that the external conditions are reflected in the actual circuit, assembly, and program designs.
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